



Material Content Data Sheet



Sales Product Name		IPD60R360P7		Issued		24. January 2018		
MA#		MA001611782						
Package		PG-TO252-3-313		Weight*		318.23 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.321	0.73	0.73	7293	7293
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		463	
wire	non noble metal	copper	7440-50-8	147.096	46.21	46.27	462233	462835
	non noble metal	aluminium	7429-90-5	0.485	0.15	0.15	1525	1525
encapsulation	organic material	carbon black	1333-86-4	1.414	0.44		4443	
	plastics	epoxy resin	-	24.742	7.77		77749	
leadfinish	inorganic material	silicondioxide	60676-86-0	115.227	36.21	44.42	362090	444282
	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11753	11753
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4464	4475
solder	non noble metal	tin	7440-31-5	0.048	0.02		150	
	noble metal	silver	7440-22-4	0.060	0.02		187	
heatspreader	non noble metal	lead	7439-92-1	2.278	0.72	0.76	7159	7496
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.03	6.04	60263	60341
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com